



TVS ARRAY SERIES

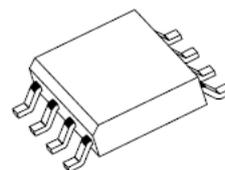
FEATURES

- ✓ Protects 3.3, 5, 12, 15, 24 V Components
- ✓ Bidirectional
- ✓ Provides Electrically Isolated Protection
- ✓ IEC 61000-4-2 (ESD) 15kV(air), 8kV(contact)
- ✓ 300 W @ 8/20 μs
- ✓ Protects 4 Lines
- ✓ SO-8 Packaging
- ✓ This is a Pb - Free Device
- ✓ All SMC parts are traceable to the wafer lot
- ✓ Additional testing can be offered upon request

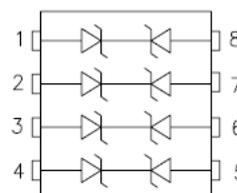
DESCRIPTION

The SMDAXXC series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect combinations of four bidirectional lines.

SO-8



SCHEMATIC & PIN CONFIGURATION



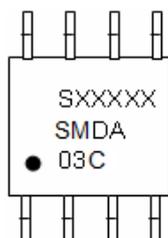
APPLICATION

- ✓ RS-232 & RS-422 Data Lines
- ✓ Microprocessor Based Equipment
- ✓ Notebooks, Desktops, & Servers
- ✓ LAN/WAN Equipment
- ✓ Serial and Parallel Port
- ✓ Peripherals

MECHANICAL CHARACTERISTICS

- ✓ SO-8 Surface Mount Package
- ✓ Approximate Weight: 0.1 grams
- ✓ PIN #1 Indicator: DOT on top of package
- ✓ Packaging: Tubes or Tape & Reel per EIA Standard 481

MARKING DIAGRAM



Where XXXXX is YYWWL

- SMDA03C = Part Name
- S = S
- YY = Year
- WW = Week
- L = Lot Number

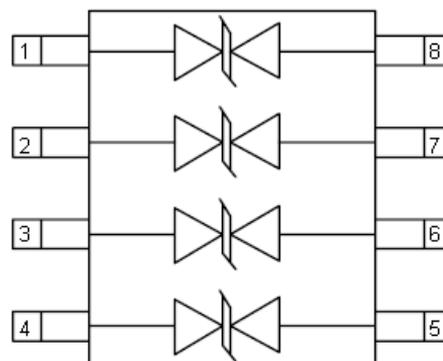
Cautions: Molding resin
Epoxy resin UL:94V-0



Circuit Diagram

The SMDAxxC series of devices are designed to protect up to four data lines. The devices are connected as follows:

- ✓ The SMDAxxC are bidirectional devices and are designed for use on line where the normal operating voltage is above ground. Pins 1, 2, 3, and 4 are connected to the protected lines. Pins 5, 6, 7, and 8 are connected to ground. Since the device is electrically symmetrical, these connections may be reversed. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.



Ordering Information:

Device	Package	Shipping
SMDA03C THRU SMDA24C	SO-8 (Pb-Free)	2500pcs / reel

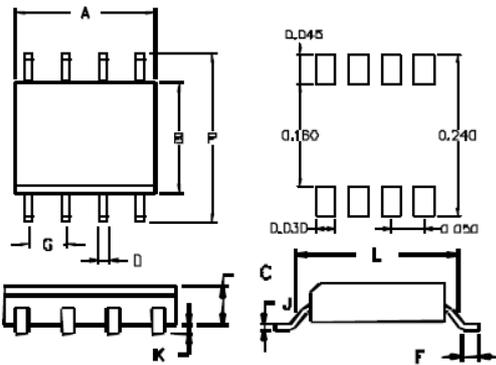
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
P	Peak Pulse Power, 8/20 μ s Waveshape	300	W
T _J	Operating Temperature	-55 to +125	$^{\circ}$ C
T _{STG}	Storage Temperature	-55 to +150	$^{\circ}$ C
T _L	Lead Soldering Temperature	260 (10 Sec.)	$^{\circ}$ C

ELECTRICAL CHARACTERISTICS @ 25 °C						
Part Number	Stand-off Voltage V_{wm} (V) Max	Breakdown Voltage V_{BR} @1mA (V) Min	Clamping Voltage V_C @ 1 A (V) Max	Leakage Current I_R @ V_{wm} (μ A) Max	Capacitance (f = 1 MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} $a(V_{BR})$ mV/°C Max
SMDA03C	3.3	4	7	200	400	-5
SMDA05C	5.0	6	9.8	40	300	1
SMDA12C	12.0	13.3	19	1	94	8
SMDA15C	15.0	16.7	24	1	70	11
SMDA24C	24.0	26.7	43	1	45	28

PACKAGE OUTLINES & DIMENSIONS



DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.189	0.196	4.8	5.0
B	0.150	0.157	3.8	4.0
C	0.053	0.069	1.35	1.75
D	0.011	0.021	0.28	0.53
F	0.016	0.050	0.41	1.27
G	0.050 BSC		1.27 BSC	
J	0.006	0.010	0.15	0.25
K	0.004	0.008	0.10	0.20
L	0.189	0.206	4.80	5.23
P	0.228	0.244	5.79	6.19

TYPICAL CHARACTERISTICS

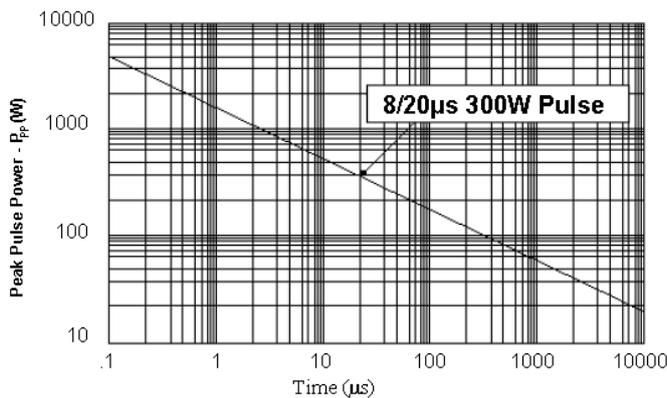


Figure 1. Peak Pulse Power Vs Pulse Time (μ s)

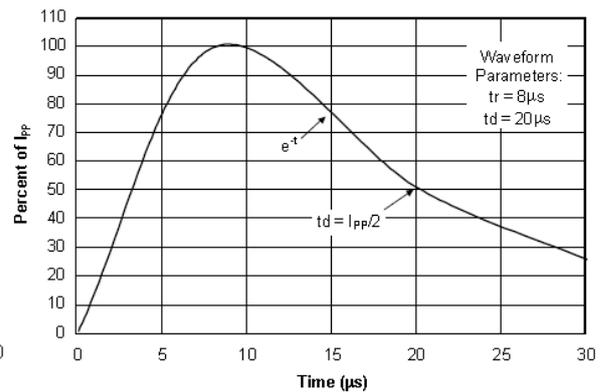


Figure 2. Pulse Wave Form



DISCLAIMER:

- 1- The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact the SMC - Sangdest Microelectronics (Nanjing) Co., Ltd sales department for the latest version of the datasheet(s).
- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
- 3- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any damages that may result from an accident or any other cause during operation of the user's units according to the datasheet(s). SMC - Sangdest Microelectronics (Nanjing) Co., Ltd assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in the datasheets.
- 4- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
- 5- No license is granted by the datasheet(s) under any patents or other rights of any third party or SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 6- The datasheet(s) may not be reproduced or duplicated, in any form, in whole or part, without the expressed written permission of SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 7- The products (technologies) described in the datasheet(s) are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations..